



**THE DATASHEET OF  
ES1CL RVG**



## 1A, 50V - 600V Surface Mount Super Fast Rectifiers

### FEATURES

- Glass passivated junction chip
- Ideal for automated placement
- Low profile package
- Low power loss, high efficiency
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21 definition



**Sub SMA**

### MECHANICAL DATA

**Case:** Sub SMA

Molding compound, UL flammability classification rating 94V-0

Moisture sensitivity level: level 1, per J-STD-020

Part No. with suffix "H" means AEC-Q101 qualified

Packing code with suffix "G" means green compound (halogen-free)

**Terminal:** Matte tin plated leads, solderable per JESD22-B102

Meet JESD 201 class 2 whisker test

**Polarity:** Indicated by cathode band

**Weight:** 0.019 g (approximately)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS (T <sub>A</sub> =25°C unless otherwise noted)										
PARAMETER	SYMBOL	ES 1AL	ES 1BL	ES 1CL	ES 1DL	ES 1FL	ES 1GL	ES 1HL	ES 1JL	UNIT
Marking code		EAL	EBL	ECL	EDL	EFL	EGL	EHL	EJL	
Maximum repetitive peak reverse voltage	V <sub>RRM</sub>	50	100	150	200	300	400	500	600	V
Maximum RMS voltage	V <sub>RMS</sub>	35	70	105	140	210	280	350	420	V
Maximum DC blocking voltage	V <sub>DC</sub>	50	100	150	200	300	400	500	600	V
Maximum average forward rectified current	I <sub>F(AV)</sub>	1								A
Peak forward surge current, 8.3 ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>	30								A
Maximum instantaneous forward voltage (Note 1) @ 1 A	V <sub>F</sub>	0.95			1.3		1.7			V
Maximum reverse current @ rated V <sub>R</sub> T <sub>J</sub> =25°C T <sub>J</sub> =125°C	I <sub>R</sub>	5 100								μA
Typical junction capacitance (Note 2)	C <sub>J</sub>	10			8					pF
Maximum reverse recovery time (Note 3)	t <sub>rr</sub>	35								ns
Typical thermal resistance	R <sub>θJL</sub> R <sub>θJA</sub>	35 85								°C/W
Operating junction temperature range	T <sub>J</sub>	- 55 to +150								°C
Storage temperature range	T <sub>STG</sub>	- 55 to +150								°C

Note 1: Pulse test with PW=300μs, 1% duty cycle

Note 2: Measured at 1 MHz and Applied V<sub>R</sub>=4.0 Volts.

Note 3: Reverse Recovery Test Conditions: I<sub>F</sub>=0.5A, I<sub>R</sub>=1.0A, I<sub>RR</sub>=0.25A

ORDERING INFORMATION					
PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING
ES1xL (Note 1)	H	RU	G	Sub SMA	1,800 / 7" Plastic reel (8mm tape)
		RV		Sub SMA	3,000 / 7" Plastic reel (8mm tape)
		RT		Sub SMA	7,500 / 13" Paper reel (8mm tape)
		MT		Sub SMA	7,500 / 13" Plastic reel (8mm tape)
		RQ		Sub SMA	10,000 / 13" Paper reel (8mm tape)
		MQ		Sub SMA	10,000 / 13" Plastic reel (8mm tape)
		R3		Sub SMA	1,800 / 7" Plastic reel (12mm tape)
		RF		Sub SMA	3,000 / 7" Plastic reel (12mm tape)
		R2		Sub SMA	7,500 / 13" Paper reel (12mm tape)
		M2		Sub SMA	7,500 / 13" Plastic reel (12mm tape)
		RH		Sub SMA	10,000 / 13" Paper reel (12mm tape)
		MH		Sub SMA	10,000 / 13" Plastic reel (12mm tape)

Note 1: "x" defines voltage from 50V (ES1AL) to 600V (ES1JL)

EXAMPLE					
PREFERRED P/N	PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION
ES1JLHRUG	ES1JL	H	RU	G	AEC-Q101 qualified Green compound

RATINGS AND CHARACTERISTICS CURVES ( $T_A=25^\circ\text{C}$  unless otherwise noted)

FIG. 1 FORWARD CURRENT DERATING CURVE

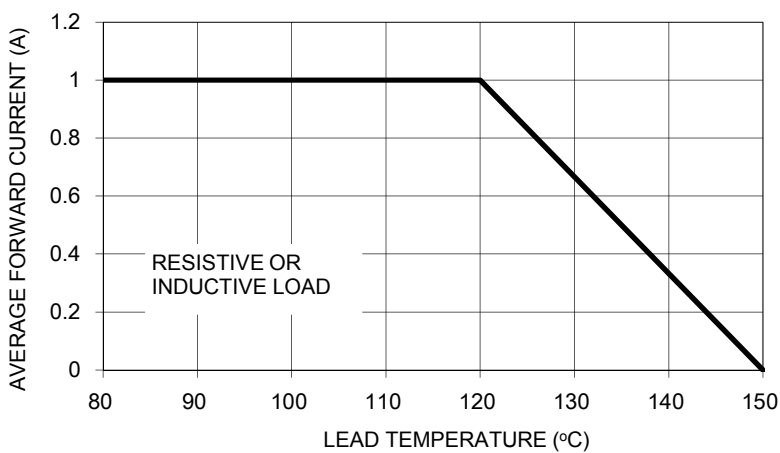


FIG. 2 TYPICAL FORWARD CHARACTERISTICS

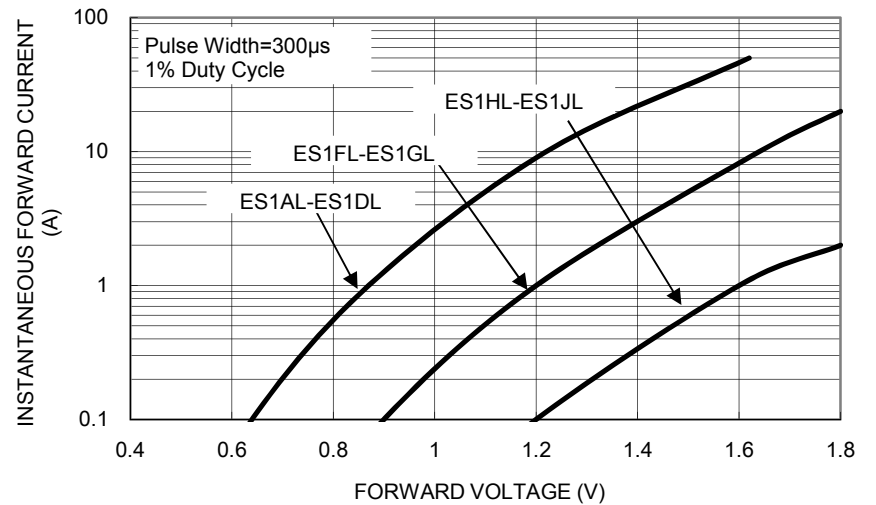


FIG. 3 MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

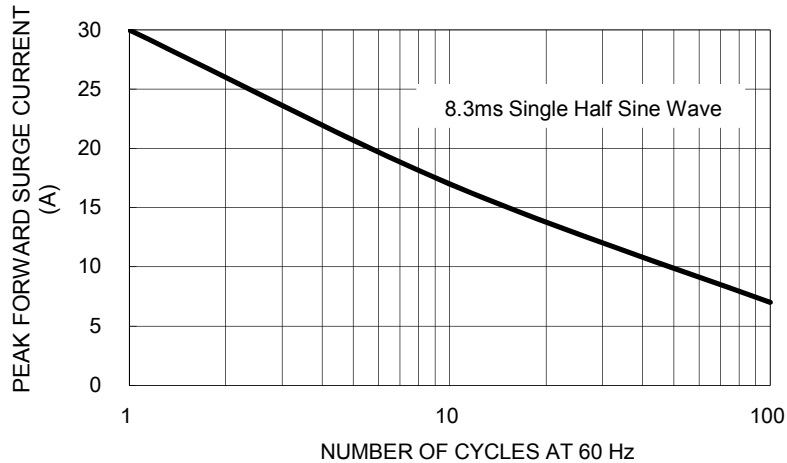


FIG. 4 TYPICAL REVERSE CHARACTERISTICS

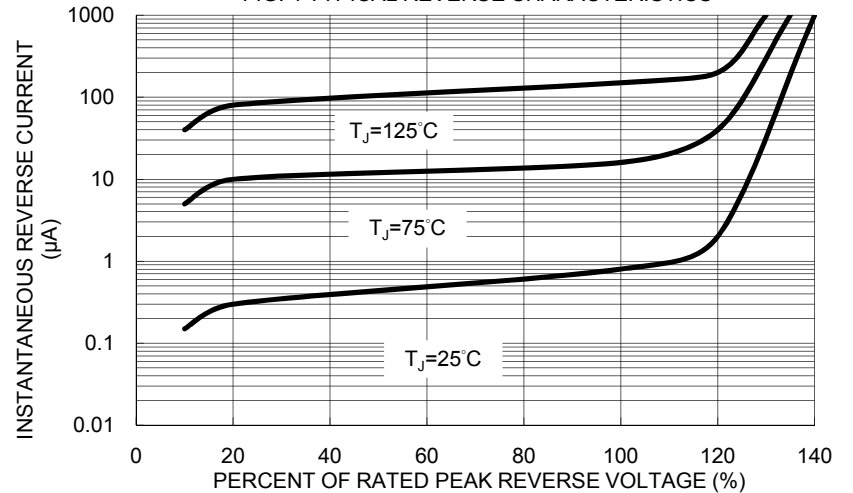


FIG. 5 TYPICAL JUNCTION CAPACITANCE

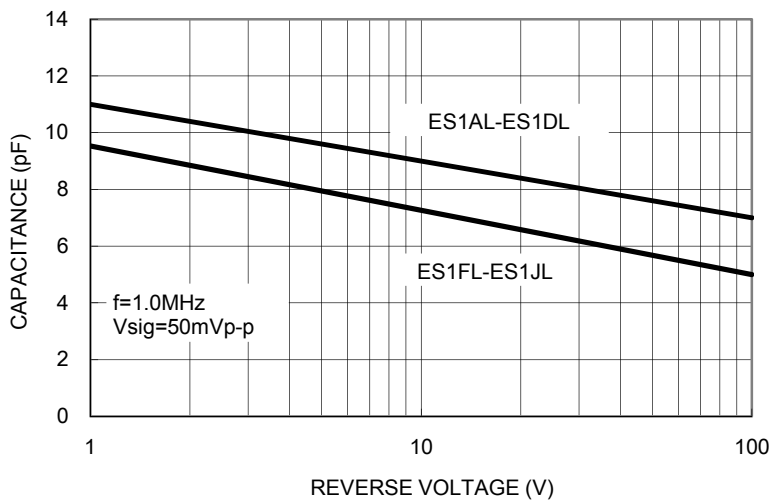
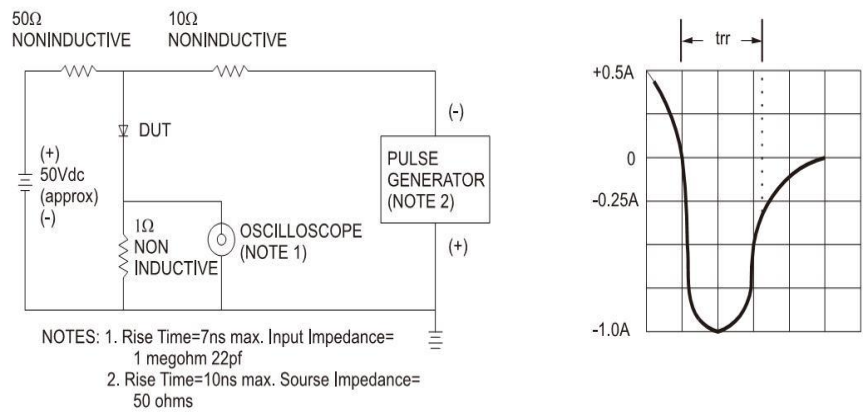
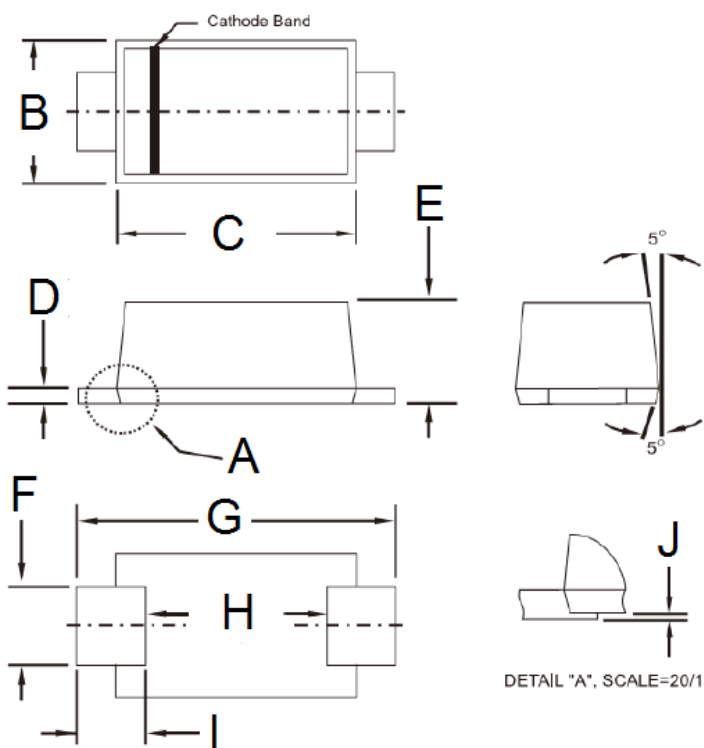


FIG.6- REVERSE RECOVERY TIME CHARACTERISTIC AND TEST CIRCUIT DIAGRAM



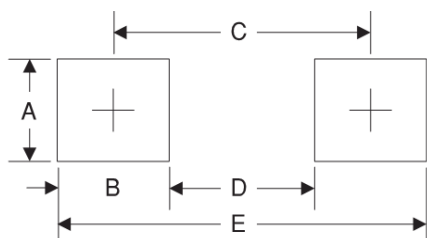
PACKAGE OUTLINE DIMENSIONS

Sub SMA



DIM.	Unit (mm)		Unit (inch)	
	Min	Max	Min	Max
B	1.70	1.90	0.067	0.075
C	2.70	2.90	0.106	0.114
D	0.16	0.30	0.006	0.012
E	1.23	1.43	0.048	0.056
F	0.80	1.20	0.031	0.047
G	3.40	3.80	0.134	0.150
H	2.45	2.60	0.096	0.102
I	0.35	0.85	0.014	0.033
J	0.00	0.10	0.000	0.004

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	1.4	0.055
B	1.2	0.047
C	3.1	0.122
D	1.9	0.075
E	4.3	0.169

MARKING DIAGRAM



- P/N = Marking Code
- G = Green compound Code
- YW = Date Code
- F = Factory Code

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